CLAIMS

1. A resin sheet for sealing an electronic component that is used to produce a resin-sealed semiconductor device,

comprising 70 to 93% by weight of an inorganic filler to the entire resin sheet for sealing an electronic component and

one or more phenol resins selected from a phenol novolac resin, a phenol aralkyl resin and a biphenyl aralkyl resin, wherein

the moisture permeability of the resin sheet after thermal curing when the resin sheet has a thickness of 250 μm is 300 g/m^2·24 hours or less under conditions of a temperature of 85°C, a humidity of 85%, and a duration of 168 hours; and

the resin sheet is produced by kneading and extrusion.

2. The resin sheet for sealing an electronic component according to claim 1, wherein

the moisture permeability of the resin sheet after thermal curing when the resin sheet has a thickness of 250 μm is 100 g/m^2·24 hours or less under conditions of a temperature of 60°C, a humidity of 90%, and a duration of 168 hours.

3. A resin-sealed semiconductor device, comprising:

an adherend;

a semiconductor chip that is flip-chip bonded to the adherend; and

a resin sheet for sealing an electronic component that seals the semiconductor chip, wherein

the resin sheet for sealing an electronic component is produced by kneading and extrusion and comprises 70 to 93% by weight of an inorganic filler to the entire resin sheet for sealing an electronic component and one or more phenol resins selected from a phenol novolac resin, a phenol aralkyl resin and a biphenyl aralkyl resin,

the moisture permeability of the resin sheet after thermal curing when the resin sheet has a thickness of 250 μm is 300 g/m^2·24 hours or less under conditions of a temperature of 85°C, a humidity of 85%, and a duration of 168 hours, and

an empty space is formed between the adherend and the semiconductor chip.

4. A resin-sealed semiconductor device comprising the resin sheet for sealing an electronic component according to claim 1 or 2.

5. A production method for a resin-sealed semiconductor device, comprising the step of:

laminating a resin sheet for sealing an electronic component from a semiconductor chip side so that the resin sheet covers a semiconductor chip that is flip-chip bonded to an adherend, wherein

the resin sheet for sealing an electronic component is produced by kneading and extrusion and comprises 70 to 93%

by weight of an inorganic filler to the entire resin sheet for sealing an electronic component and one or more phenol resins selected from a phenol novolac resin, a phenol aralkyl resin and a biphenyl aralkyl resin, and

the moisture permeability of the resin sheet after thermal curing when the resin sheet has a thickness of 250 μm is 300 g/m^2·24 hours or less under conditions of a temperature of 85°C, a humidity of 85%, and a duration of 168 hours.